

Based Material Line Up



SH260/SH260B

1. CORE (C-STAGE)

	Thickness		ply-up	RC (%)	Dk			Df		
	mm	mil			1 GHz*	3 GHz	10 GHz	1 GHz*	3 GHz	10 GHz
Excluding copper thickness (H and 1OZ are the most commonly used)	0.076	3	1x1080	59	3.77	3.79	3.74	0.010	0.011	0.011
	0.10	4	1x2313	51	3.95	3.98	3.94	0.009	0.010	0.010
	0.127	5	1x2116	50	4.00	4.01	3.98	0.009	0.010	0.010
	0.15	6	2x1080	59	3.77	3.79	3.74	0.010	0.011	0.011
	0.20	8	1x7628	41	4.24	4.30	4.26	0.009	0.009	0.009
	0.25	10	2x2116	50	4.00	4.01	3.98	0.009	0.010	0.010
	0.30	12	2x2116+1080	50	4.00	4.01	3.98	0.009	0.010	0.010
	0.38	15	2x7628	41	4.24	4.30	4.26	0.009	0.009	0.009
	0.51	20	2x7628+2x1080	44	4.13	4.20	4.17	0.009	0.009	0.010
	0.71	28	4x7628	38	4.32	4.38	4.34	0.008	0.009	0.009
Including copper thickness	1.0 H/H	39	4X7628+2X2116	41	4.24	4.30	4.26	0.009	0.009	0.009
	1.0 1/1	39	4X7628+2X2116	40	4.27	4.31	4.27	0.008	0.009	0.009
	1.2 H/H	47	5X7628+2X2116	41	4.24	4.30	4.26	0.009	0.009	0.009
	1.2 1/1	47	5X7628+2X2116	40	4.27	4.31	4.27	0.008	0.009	0.009
	1.5 H/H	59	8X7628	39	4.29	4.33	4.29	0.008	0.009	0.009
	1.5 1/1	59	7X7628+2X1080	41	4.24	4.30	4.26	0.009	0.009	0.009
	1.6 H/H	63	7X7628+2X2116	41	4.24	4.30	4.26	0.009	0.009	0.009
	1.6 1/1	63	7X7628+2X2116	41	4.24	4.30	4.26	0.009	0.009	0.009

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2. PREPREG (B-STAGE)

Glass style	RC (%) Nominal	Thickness		Dk			Df		
		mm	mil	1GHz*	3GHz	10GHz	1 GHz*	3 GHz	10 GHz
106	72	0.060	2.40	3.50	3.53	3.48	0.011	0.012	0.012
1080	63	0.085	3.30	3.70	3.71	3.67	0.011	0.011	0.011
2313	55	0.110	4.30	3.85	3.89	3.85	0.010	0.010	0.011
2116	50	0.125	4.90	4.00	4.01	3.98	0.009	0.010	0.010
7628	40	0.195	7.70	4.27	4.31	4.27	0.008	0.009	0.009

3. REMARK

- 1) *1GHz is tested by parallel plate method. Others are tested by SPDR method
- 2) The data above show actual values and are not guaranteed.
- 3) RC* is not common type for reference.
- 4) Last update: July, 2019